



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Jun-ichiro FURIHATA et al.

Group Art Unit: 1745

Application No.: 10/690,541

Examiner: J. RHEE

Filed: October 23, 2003

Docket No.: 108868.01

For: A METHOD OF PRODUCING A BONDED WAFER AND THE BONDED WAFER

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Pursuant to 37 CFR §1.56, the attention of the Patent and Trademark Office is hereby directed to the reference(s) listed on the attached PTO-1449. Unless otherwise indicated herein, one copy of each reference is attached. It is respectfully requested that the information be expressly considered during the prosecution of this application, and that the reference(s) be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

☒ 1. This Information Disclosure Statement is being filed more than three months after the U.S. filing date and after the mailing date of a Final Rejection, Notice of Allowance, or other action that closes prosecution (e.g., Quayle Action), but before payment of the Issue Fee. Attached is our Check No. 171228 in the amount of \$180.00 in payment of the fee under 37 CFR §1.17(p). Please credit or debit Deposit Account No. 15-0461 as needed to ensure consideration of the disclosed information. Two duplicate copies of this paper are attached.

☒ a. I hereby certify that each item of information contained in this Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this Information Disclosure Statement. 37 CFR §1.97(e)(1).

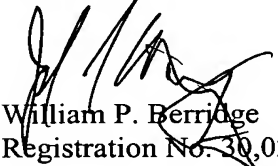
09/28/2005 HALI11 00000002 10690541

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- ☒ 2. The references were cited in a counterpart foreign application. An English language version of the foreign search report is attached for the Examiner's information. The remaining reference cited in the foreign search report has already been cited and considered by the Examiner.

Respectfully submitted,

  
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WPB:JSA/dmw

Date: September 26, 2005

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<p><b>DEPOSIT ACCOUNT USE AUTHORIZATION</b> Please grant any extension necessary for entry; Charge any fee due to our Deposit Account No. 15-0461</p>
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Sheet 1 of 1

Form PTO-1449 (REV. 8-83)  INFORMATION DISCLOSURE STATEMENT  (Use several sheets if necessary)		U.S. DEPT. of Commerce PATENT & TRADEMARK OFFICE		ATTY DOCKET NO. 108868.01		APPLICATION NO. 10/690,541	
		APPLICANT(S) Jun-ichiro FURIHATA et al.					
		FILING DATE October 23, 2003		GROUP 1745			
U.S. PATENT DOCUMENTS							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	
		4,588,473	05/13/1986	HISATOMI et al.			
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	
		EP 0 460 437 A2	12/11/1991	EUROPE			
		EP 0 797 248 A2	09/24/1997	EUROPE			
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)							
		Mitani K. et al: "Contribution of Polished Surface Waviness to Final SOI Thickness Uniformity of Bonded Wafers through PACE Process"; IEICE Transactions on Electronics, Institute of Electronics Information and Comm. Eng., Tokyo, JP; Vol. E80-C, No. 3, March 1997 (1997-03), pages 370-377.					
EXAMINER					DATE CONSIDERED		
Examiner: Initial if citation considered, whether or not citation is in conformance with M.P.E.P. 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							

Date: September 26, 2005